# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT OF ASSIGNOR'S INTEREST

#### **CONVEYING PARTY DATA**

Name	Execution Date
Naohisa Kitazato	2000-03-10
Junya Saito	2000-03-13
Kenichi Murata	2000-03-10
Yasushi Katayama	2000-03-15

### **RECEIVING PARTY DATA**

Name	Street Address	Internal Address	City	State/Country	Postal Code
Sony Corporation	7-35, Kitashinagawa 6- chome	Shinagawa-Ku	Tokyo	JP	141-0001

### PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number	11217917	

## **CORRESPONDENCE DATA**

**FAX NUMBER**: (908) 654-0415

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.

**CUSTOMER NUMBER: 000530** 

NAME OF PERSON SIGNING:	Orville R. Cockings
DATE SIGNED:	2006-04-27

Total Attachments: 2

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PATENT REEL: 017545 FRAME: 0112

Docket Number: SONYJP 3.3-076 CONT SONY REFERENCE NO. S99P0797US00

#### ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

Data transmission control method, data transmitting method, data transmitting apparatus, and receiving apparatus

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 09/521,098Filing Date: March 7, 2000

This assignment executed on the dates indicated below.

Naohisa Kitazato	March 10, 2000		
Name of First or Sole Inventor	Execution Date of U.S. Patent Application		
Tokyo, Japan	· · · · · · · · · · · · · · · · · · ·		
Residence of First or Sole Inventor			
Nadara Velazati	March. 10, 2000		
Signature of First or Sole Inventor	Date of this Assignment		

PATENT REEL: 017545 FRAME: 0113

Docket Number: SONYJP 3.3-076 CONT

Junya Saito	March 13, 2000	
Name of Second Joint Inventor	Execution Date of U.S. Patent Application	
Saitama, Japan		
Residence of Second Joint Inventor		
Junya Santo	March. 13. 2000	
Signature of Second Joint Inventor	Date of this Assignment	
Kenichi Murata	March 10, 2000	
Name of Third Joint Inventor	Execution Date of U.S. Patent Application	
Tokyo, Japan		
Residence of Third Joint Inventor		
Henichi Manata	March 10, 2000	
Signature of Third Joint Inventor	Date of this Assignment	
Yasushi Katayama	March 15, 2000	
Name of Fourth Joint Inventor	Execution Date of U.S. Patent Application	
Tokyo, Japan		
Residence of Fourth Joint Inventor		
Yasushi Katayama	March 18, 2000	
Signature of Fourth Joint Inventor	Date of this Assignment	
Name of Fifth Joint Inventor	Execution Date of U.S. Patent Application	
Residence of Fifth Joint Inventor	···········	
Signature of Fifth Joint Inventor	Date of this Assignment	

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PATENT REEL: 017545 FRAME: 0114

**RECORDED: 04/28/2006**